



INTERNATIONAL STANDARD



**Printed electronics –
Part 202-3: Materials – Conductive ink – Measurement of sheet resistance of
conductive films – Contactless method**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

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Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62899 series, published under the general title *Printed electronics*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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INTRODUCTION

Conductive films, transparent or non-transparent, are a key element for electronic products. A widespread method used for the measurement of the sheet resistance of conductive films is the 4-point probe measurement. Nevertheless, making an electrical contact with the probes is sometimes critical for the measurement. For some devices or films which are covered with an insulating layer or composed of micro-/nano-structures, establishing an electrical contact is difficult, which makes the 4-point probe method not suitable for the measurement of sheet resistance (see Table A.1 and Figures A.1 and A.2 in Annex A). The 4-point probe method is also sensitive to contact force and layer thickness. The eddy-current-based measurement method, which does not require electrical contact, is widely used for this purpose in the industry. This document specifies a standard method for measurement of sheet resistance using a contactless eddy-current method.

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1 Scope

This part of IEC 62899 defines terms and specifies a standard method for the measurement of the sheet resistance of printed conductive films using a contactless eddy-current method.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 62899-202, *Printed electronics – Materials – Part 202: Conductive ink*